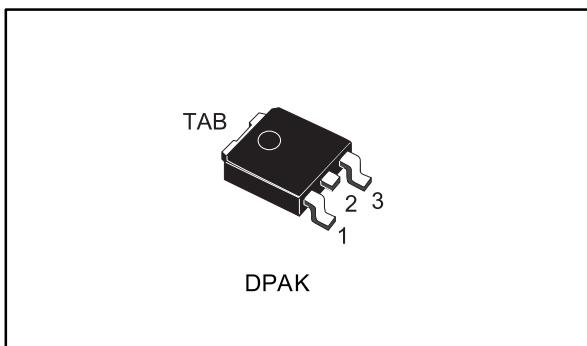
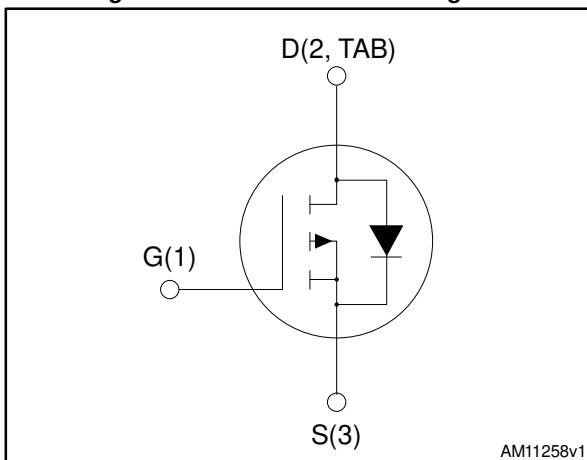


## Automotive-grade P-channel -40 V, 12 mΩ typ., -50 A STripFET™ F6 Power MOSFET in a DPAK package

Datasheet - production data



**Figure 1: Internal schematic diagram**



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STD45P4LLF6AG	-40 V	15 mΩ	-50 A

- Designed for automotive applications and AEC-Q101 qualified
- Very low on-resistance
- Very low gate charge
- High avalanche ruggedness
- Low gate drive power loss

### Applications

- Switching applications

### Description

This device is a P-channel Power MOSFET developed using the STripFET™ F6 technology, with a new trench gate structure. The resulting Power MOSFET exhibits very low R<sub>DS(on)</sub> in all packages.

**Table 1: Device summary**

Order code	Marking	Package	Packing
STD45P4LLF6AG	45P4LLF6	DPAK	Tape and reel

**Contents**

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# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	-40	V
$V_{GS}$	Gate-source voltage	$\pm 18$ V	V
$I_D$	Drain current (continuous) at $T_{case} = 25$ °C	-50	A
	Drain current (continuous) at $T_{case} = 100$ °C	-31	
$I_{DM}^{(1)}$	Drain current (pulsed)	-200	A
$P_{TOT}$	Total dissipation at $T_{case} = 25$ °C	58	W
$E_{AS}^{(2)}$	Single pulse avalanche energy	160	mJ
$T_{stg}$	Storage temperature	-55 to 150	°C
$T_j^{(3)}$	Operating junction temperature		

**Notes:**

(1) Pulse width is limited by safe operating area.

(2) starting  $T_j = 25$  °C,  $R_G = 47$  Ω,  $I_{D(min)} = -25$  A.(3) HTRB performed at  $T_j = 175$  °C,  $V_{DS} = 100\%$   $V_{(BR)DSS}$ .**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	2.14	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient	50	

## 2 Electrical characteristics

( $T_{case} = 25^\circ C$  unless otherwise specified)

**Table 4: Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 V, I_D = -250 \mu A$	-40			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0 V, V_{DS} = -40 V$			-1	$\mu A$
		$V_{GS} = 0 V, V_{DS} = -40 V, T_{case} = 125^\circ C$			-10	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0 V, V_{GS} = -18 V$			-100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1		-2.5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = -10 V, I_D = -25 A$		12	15	$m\Omega$
		$V_{GS} = -4.5 V, I_D = -25 A$		17	20	

**Table 5: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = -25 V, f = 1 MHz, V_{GS} = 0 V$	-	3525	-	pF
$C_{oss}$	Output capacitance		-	345	-	
$C_{rss}$	Reverse transfer capacitance		-	240	-	
$Q_g$	Total gate charge	$V_{DD} = -20 V, I_D = -50 A, V_{GS} = -10 V$ (see <i>Figure 14: "Gate charge test circuit"</i> )	-	65.5	-	nC
$Q_{gs}$	Gate-source charge		-	11.5	-	
$Q_{gd}$	Gate-drain charge		-	13	-	

**Table 6: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = -20 V, I_D = -25 A, R_G = 4.7 \Omega, V_{GS} = -10 V$ (see <i>Figure 13: "Switching times test circuit for resistive load"</i> )	-	12	-	ns
$t_r$	Rise time		-	35.5	-	
$t_{d(off)}$	Turn-off delay time		-	63.5	-	
$t_f$	Fall time		-	31	-	

Table 7: Source-drain diode

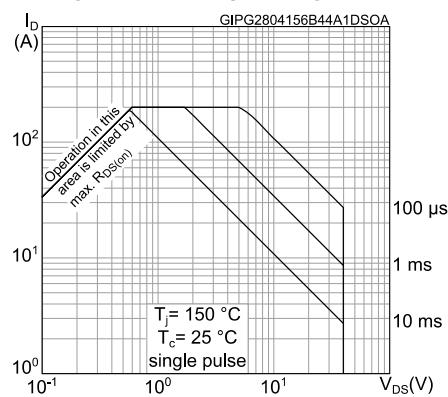
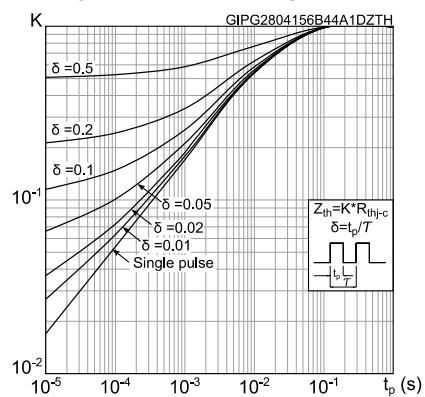
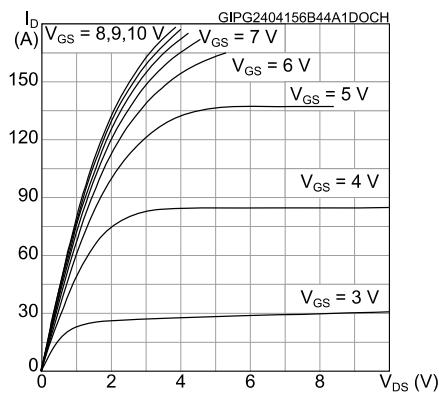
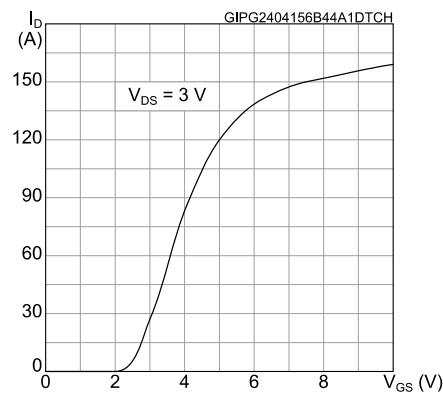
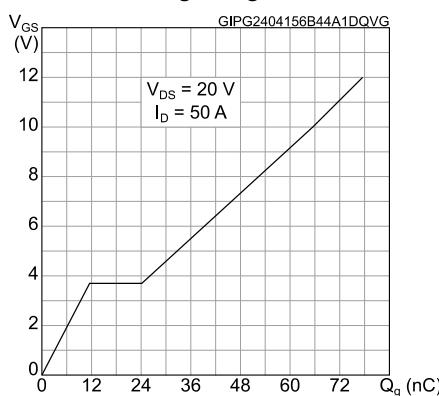
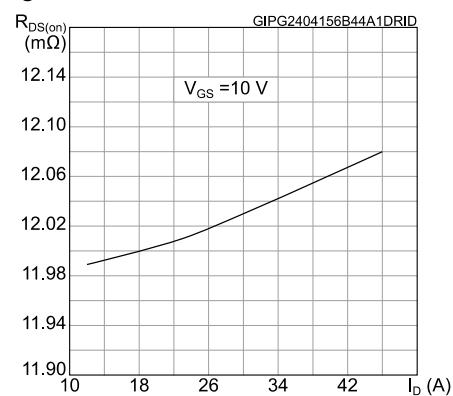
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		-50	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		-200	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}$ , $I_{SD} = -50 \text{ A}$	-		-1.3	V
$t_{rr}$	Reverse recovery time	$I_{SD} = -50 \text{ A}$ , $dI/dt = -100 \text{ A}/\mu\text{s}$ , $V_{DD} = -32 \text{ V}$ (see <i>Figure 15: "Test circuit for inductive load switching and diode recovery times"</i> )	-	27.5		ns
$Q_{rr}$	Reverse recovery charge		-	24.5		nC
$I_{RRM}$	Reverse recovery current		-	-1.8		A

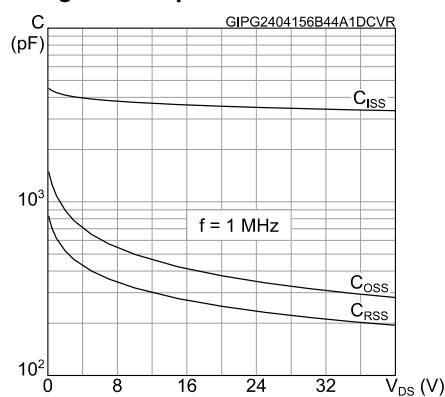
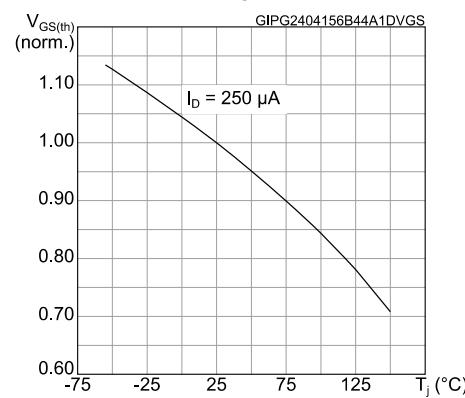
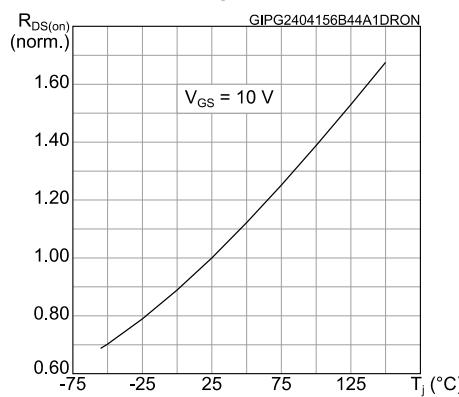
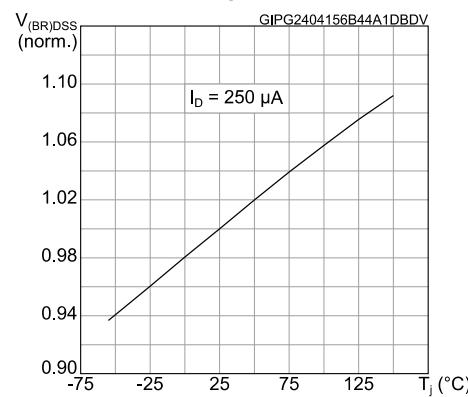
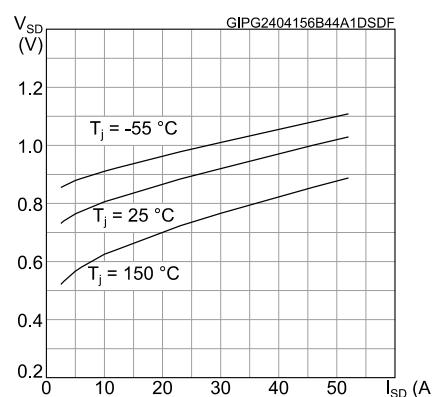
**Notes:**

(1) Pulse width is limited by safe operating area.

(2) Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

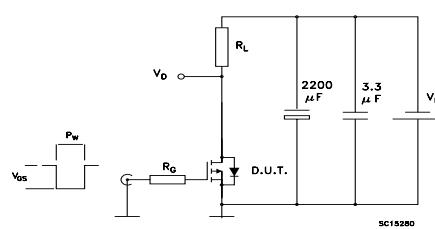
**Figure 2: Safe operating area****Figure 3: Thermal impedance****Figure 4: Output characteristics****Figure 5: Transfer characteristics****Figure 6: Gate charge vs gate-source voltage****Figure 7: Static drain-source on-resistance**

**Figure 8: Capacitance variations****Figure 9: Normalized gate threshold voltage vs temperature****Figure 10: Normalized on-resistance vs temperature****Figure 11: Normalized V(BR)DSS vs temperature****Figure 12: Source-drain diode forward characteristics**

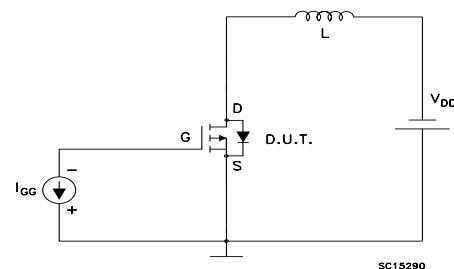
For the P-channel Power MOSFET, current and voltage polarities are reversed.

### 3 Test circuits

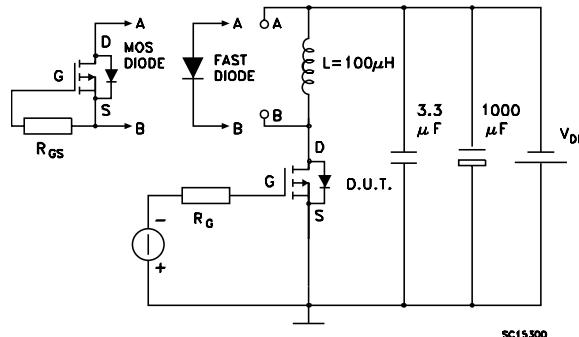
**Figure 13: Switching times test circuit for resistive load**



**Figure 14: Gate charge test circuit**



**Figure 15: Test circuit for inductive load switching and diode recovery times**

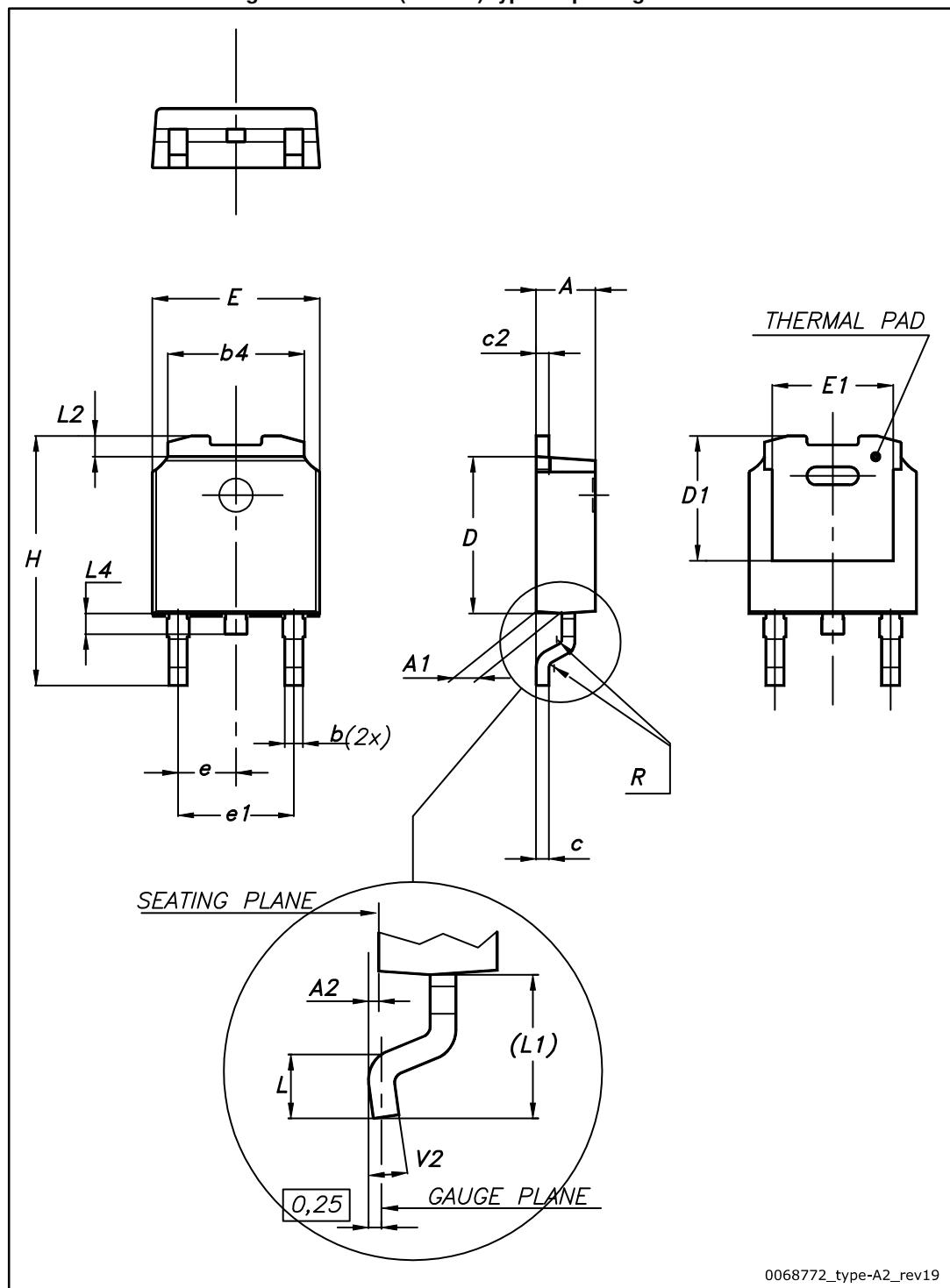


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK® is an ST trademark.

## 4.1 DPAK (TO-252) type A2 package information

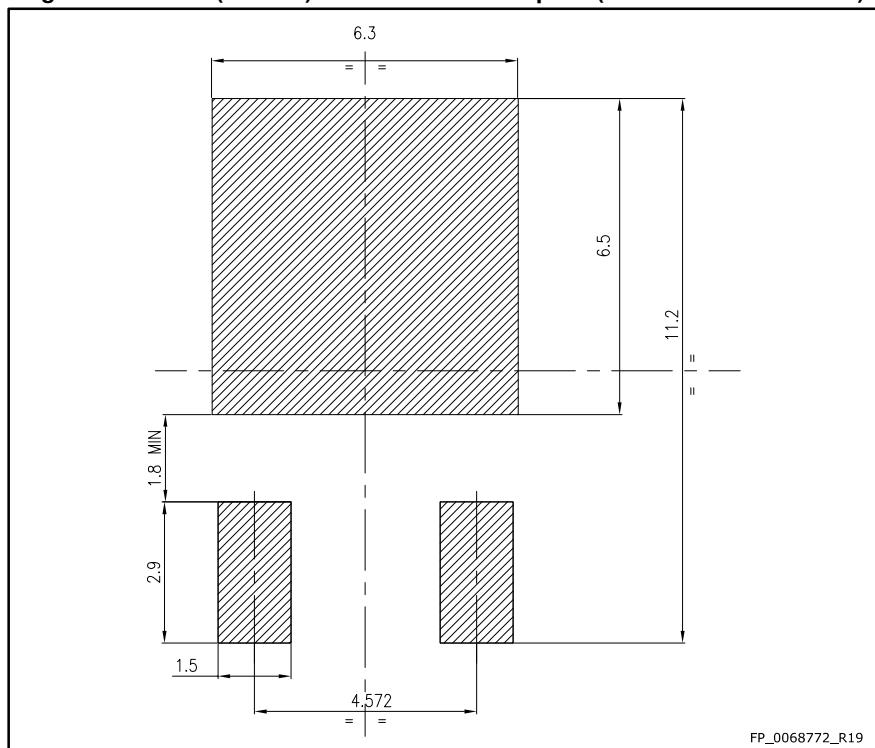
Figure 16: DPAK (TO-252) type A2 package outline



**Table 8: DPAK (TO-252) type A2 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.16	2.28	2.40
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

Figure 17: DPAK (TO-252) recommended footprint (dimensions are in mm)



FP\_0068772\_R19

## 4.2 DPAK (TO-252) packing information

Figure 18: DPAK (TO-252) tape outline

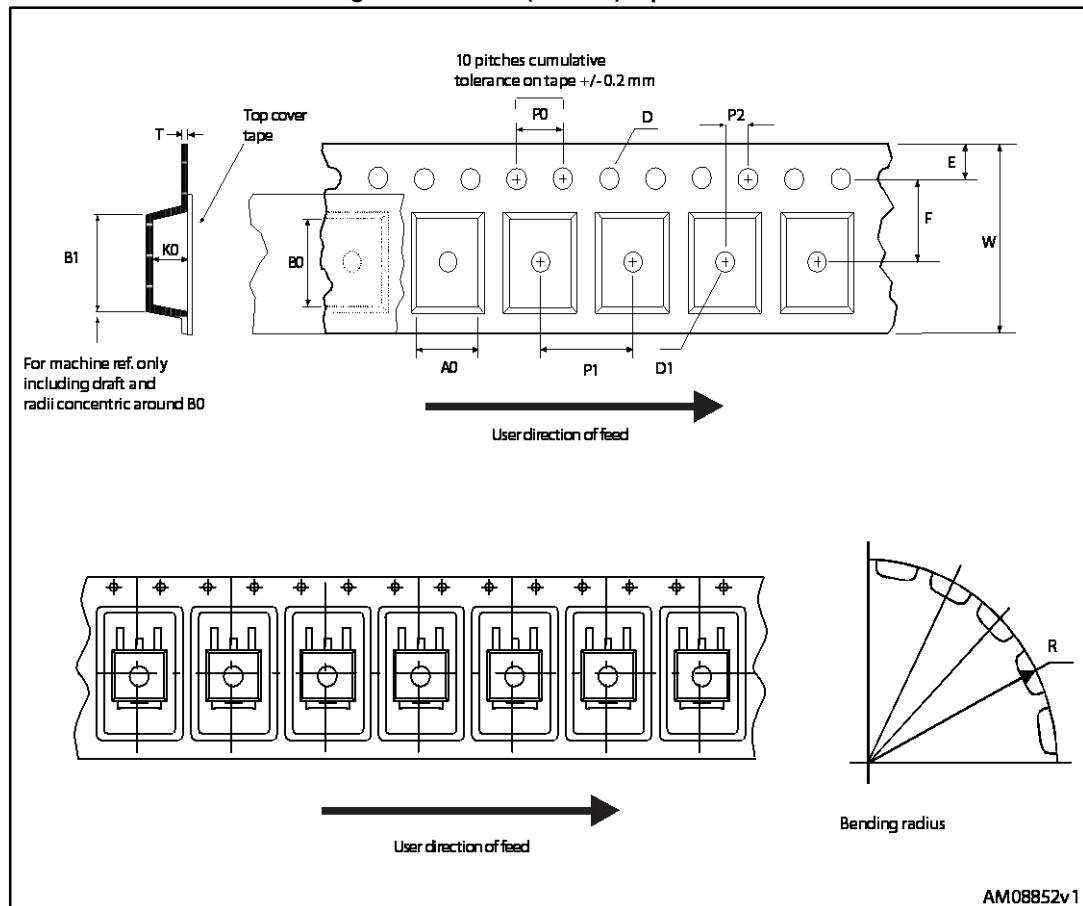


Figure 19: DPAK (TO-252) reel outline

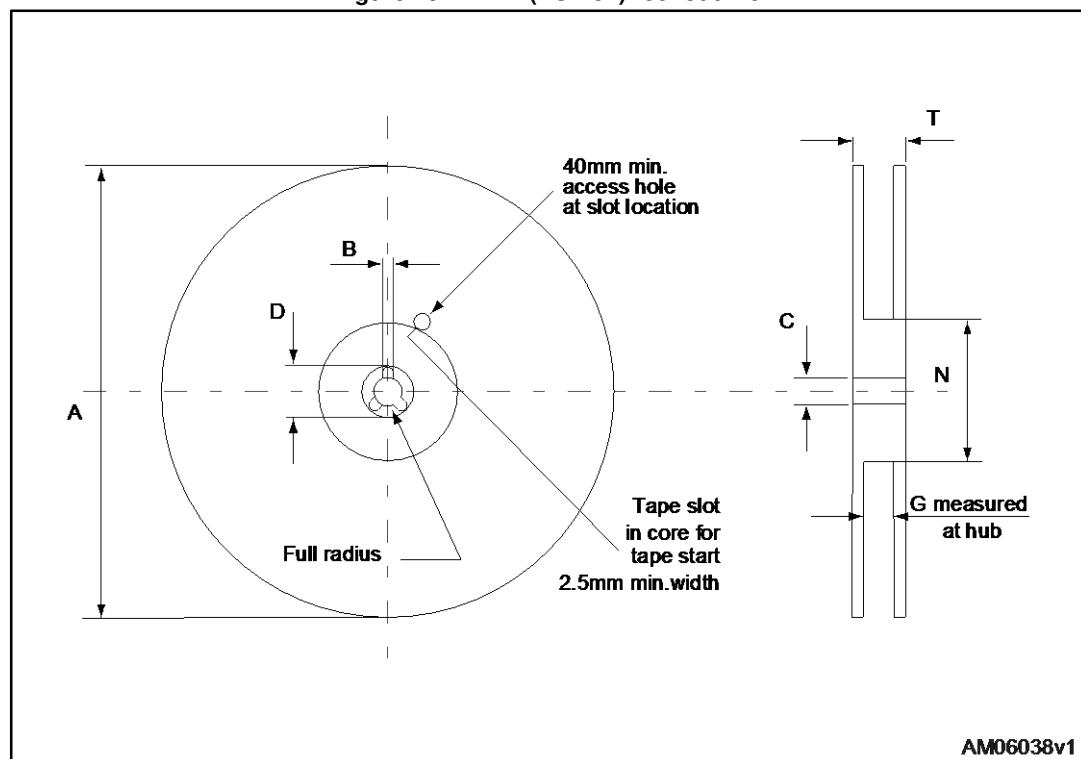


Table 9: DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

## 5 Revision history

**Table 10: Document revision history**

Date	Revision	Changes
28-Apr-2015	1	First release.
22-Jul-2015	2	Modified: $V_{GS}$ values in absolute maximum ratings table and static table. Updated: DPAK (TO-252) type A2 package information section updated. Minor text changes.

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